

FEATURES

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

BVDSS	RDS ON	ID
-30V	8.7mΩ	-50A

General Description

DFN 3X3 Pin Configuration

The JHBB3115 is the high cell density trenched P-ch MOSFETs, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications.

The JHBB3115 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

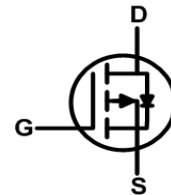
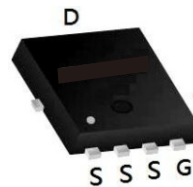


Table1 Absolute Maximum Ratings (Tc=25°C, unless otherwise specified)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-50	A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ -10V ¹	-32	A
I _{DM}	Pulsed Drain Current ²	-200	A
EAS	Single Pulse Avalanche Energy ³	125	mJ
I _{AS}	Avalanche Current	-50	A
P _D @T _C =25°C	Total Power Dissipation ⁴	38	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	65	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	2.3	°C/W

Table 2. Thermal Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30	---	---	V
$R_{DS(ON)}$	Static Drain -Source On -Resistance ²	$V_{GS}=-10V, I_D=-30A$	---	7.3	8.7	mΩ
		$V_{GS}=-4.5V, I_D=-1.5A$	---	11	13.5	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.2	---	-2.5	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-24V, V_{GS}=0V, T_J=25^\circ C$	---	---	-1	μA
		$V_{DS}=-24V, V_{GS}=0V, T_J=55^\circ C$	---	---	-5	
I_{GSS}	Gate -Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=-5V, I_D=-30A$	---	25	---	S
Q_g	Total Gate Charge (-4.5V)	$V_{DS}=-15V, V_{GS}=-4.5V, I_D=-1.5A$	---	30	---	nC
Q_{gs}	Gate -Source Charge		---	10	---	
Q_{gd}	Gate -Drain Charge		---	10.4	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-15V, V_{GS}=-10V, R_G=3.3\Omega$ $I_D=-1.5A$	---	9.4	---	ns
T_r	Rise Time		---	10.2	---	
$T_{d(off)}$	Turn-Off Delay Time		---	117	---	
T_f	Fall Time		---	24	---	
C_{iss}	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V, f=1MHz$	---	3448	---	pF
C_{oss}	Output Capacitance		---	508	---	
C_{rss}	Reverse Transfer Capacitance		---	421	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current ^{1,5}	$V_G=V_D=0V, \text{Force Current}$	---	---	-50	A
I_{SM}	Pulsed Source Current ²		---	---	-13.0	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V, I_S=-1A, T_J=25^\circ C$	---	---	-1	V
t_{rr}	Reverse Recovery Time	$I_F=-1.5A, di/dt=100A/\mu s,$	---	20	---	nS
Q_{rr}	Reverse Recovery Charge	$T_J=25^\circ C$	---	9.5	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch ²FR -4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD}=-25V, V_{GS}=-10V, L=0.1mH, I_{AS}=-50A$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as $I_{D,}$ in real applications , should be limited by total power dissipation.

Typical Characteristics

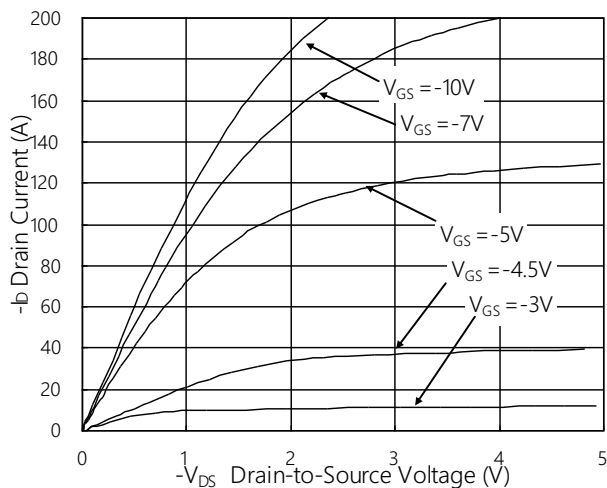


Fig.1 Typical Output Characteristics

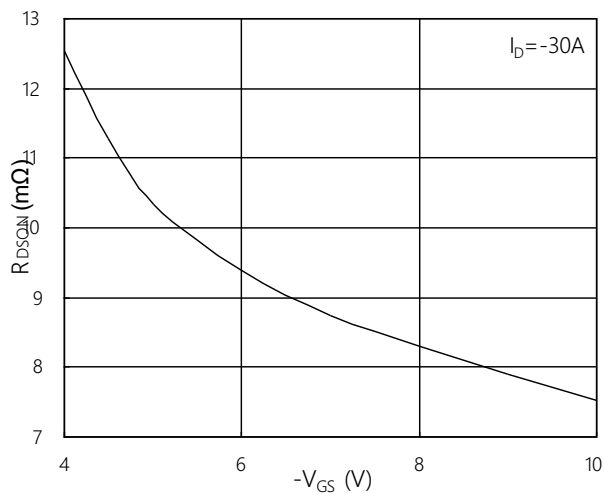


Fig.2 On-Resistance v.s Gate-Source

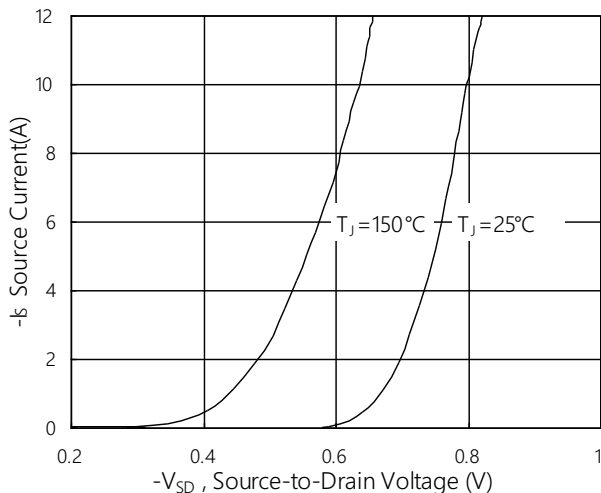


Fig.3 Forward Characteristics of Reverse

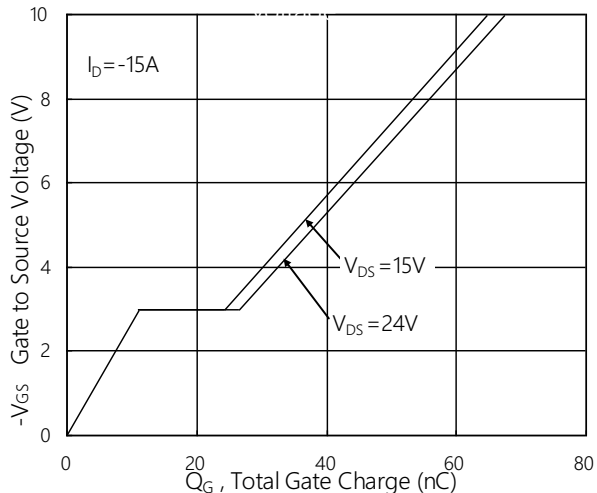


Fig.4 Gate-Charge Characteristics

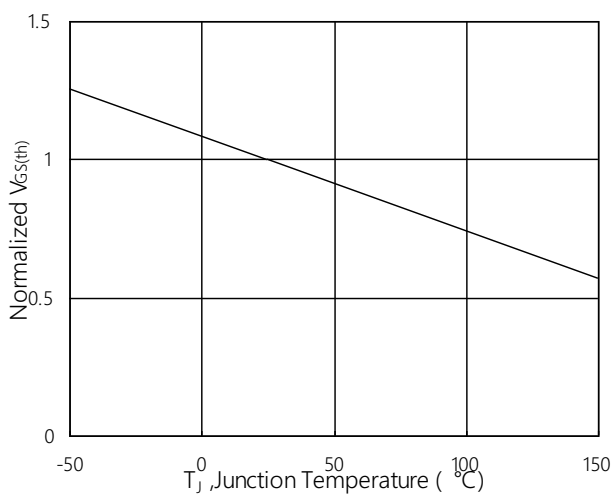


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

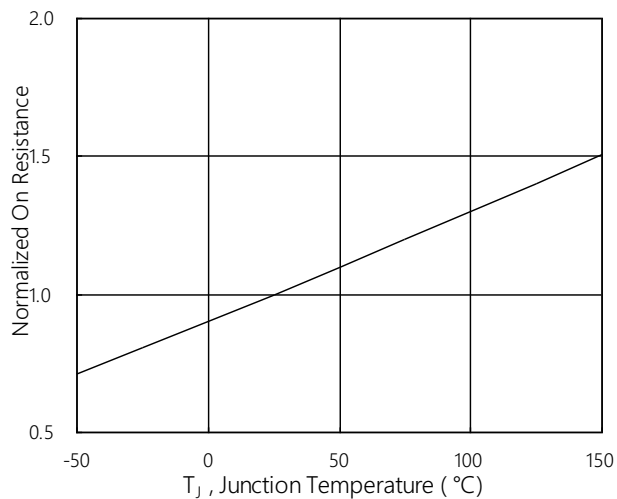


Fig.6 Normalized $R_{DS(on)}$ v.s T_J

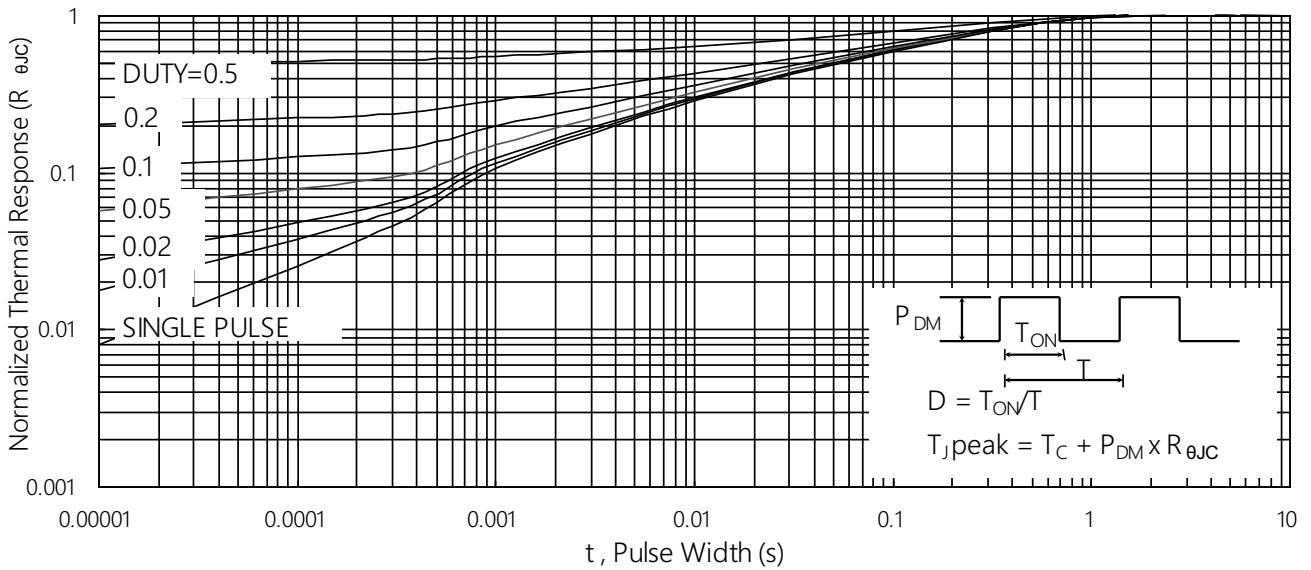
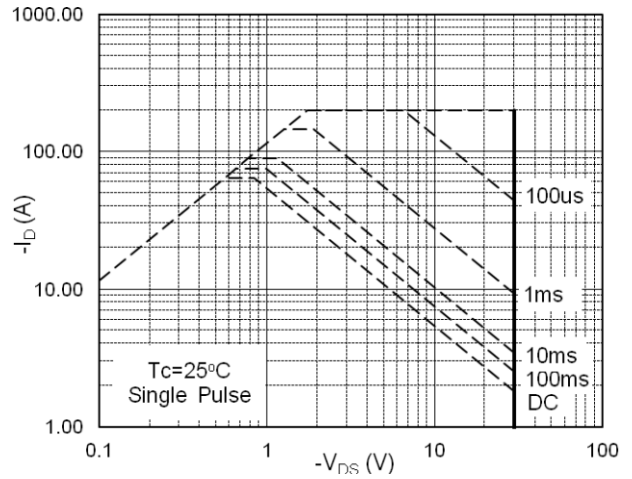
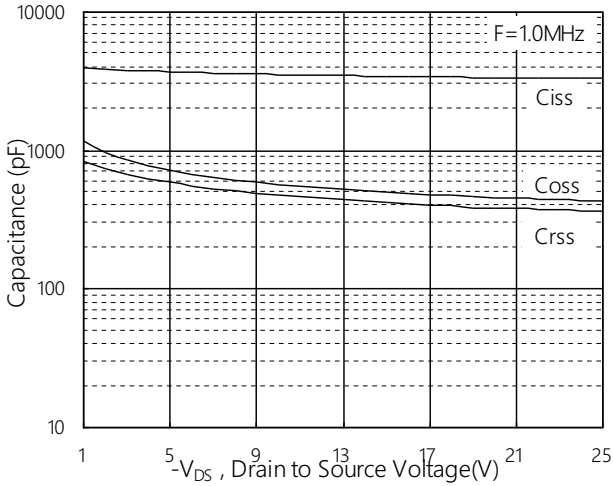


Fig. 9 Normalized Maximum Transient Thermal Impedance

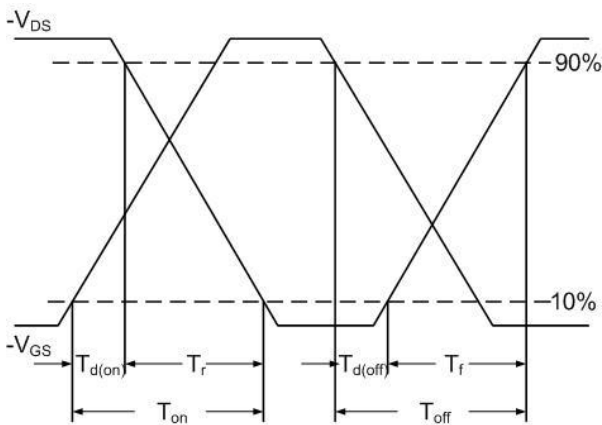


Fig. 10 Switching Time Waveform

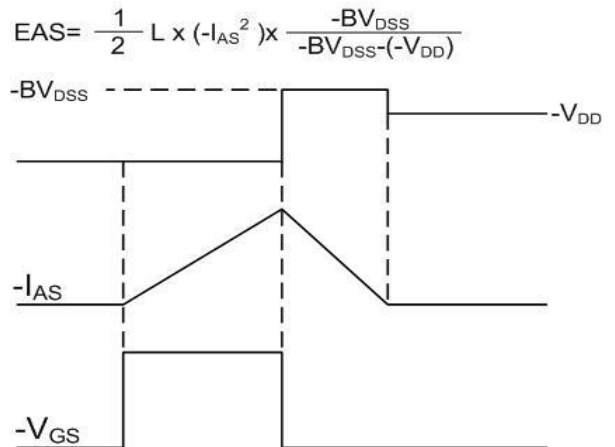
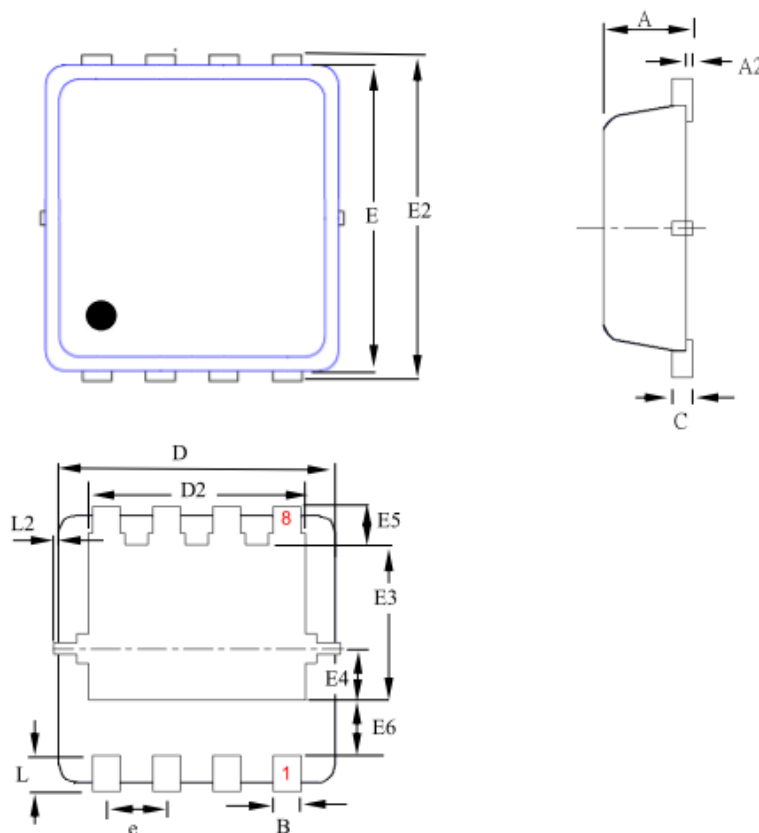


Fig. 11 Unclamped Inductive Switching Waveform

DFN3*3 Package Outline Dimensions



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.80	0.90	0.028	0.031	0.035
A2	0.00	--	0.05	0.000	--	0.002
B	0.24	0.30	0.35	0.009	0.012	0.014
C	0.10	0.15	0.25	0.004	0.006	0.010
D	2.90	3.00	3.20	0.114	0.118	0.126
D2	2.15	2.35	2.59	0.085	0.093	0.102
E	2.90	3.00	3.12	0.114	0.118	0.123
E2	3.05	3.20	3.45	0.120	0.126	0.136
E3	1.55	1.75	1.95	0.061	0.069	0.077
E4	0.48	0.58	0.68	0.019	0.023	0.027
E5	0.28	0.43	0.58	0.011	0.017	0.023
E6	0.43	0.63	0.87	0.017	0.025	0.034
L	0.30	0.40	0.50	0.012	0.016	0.020
L2	0.00	--	0.10	0.000	--	0.004
e	--	0.65	--	--	0.026	--

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